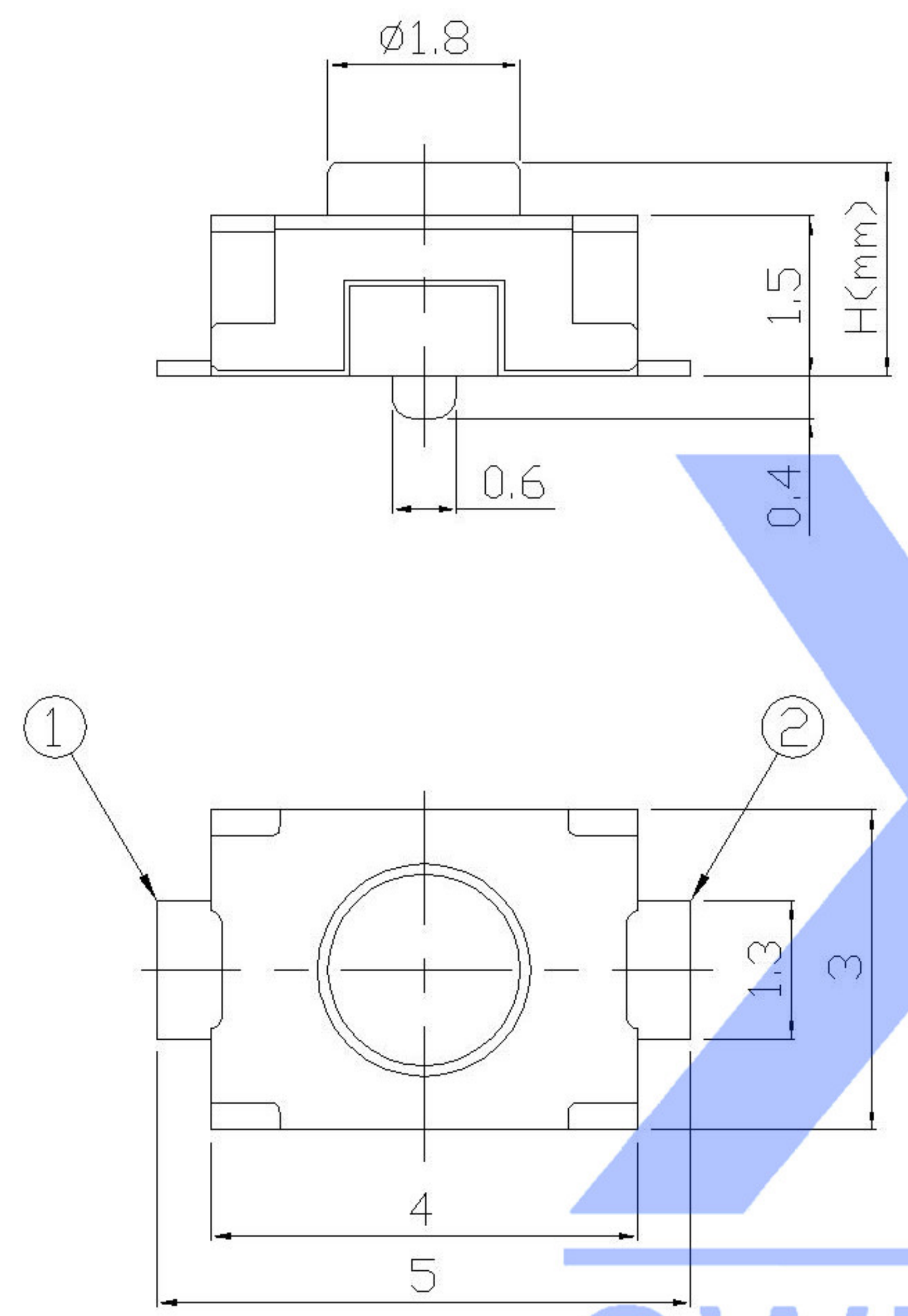
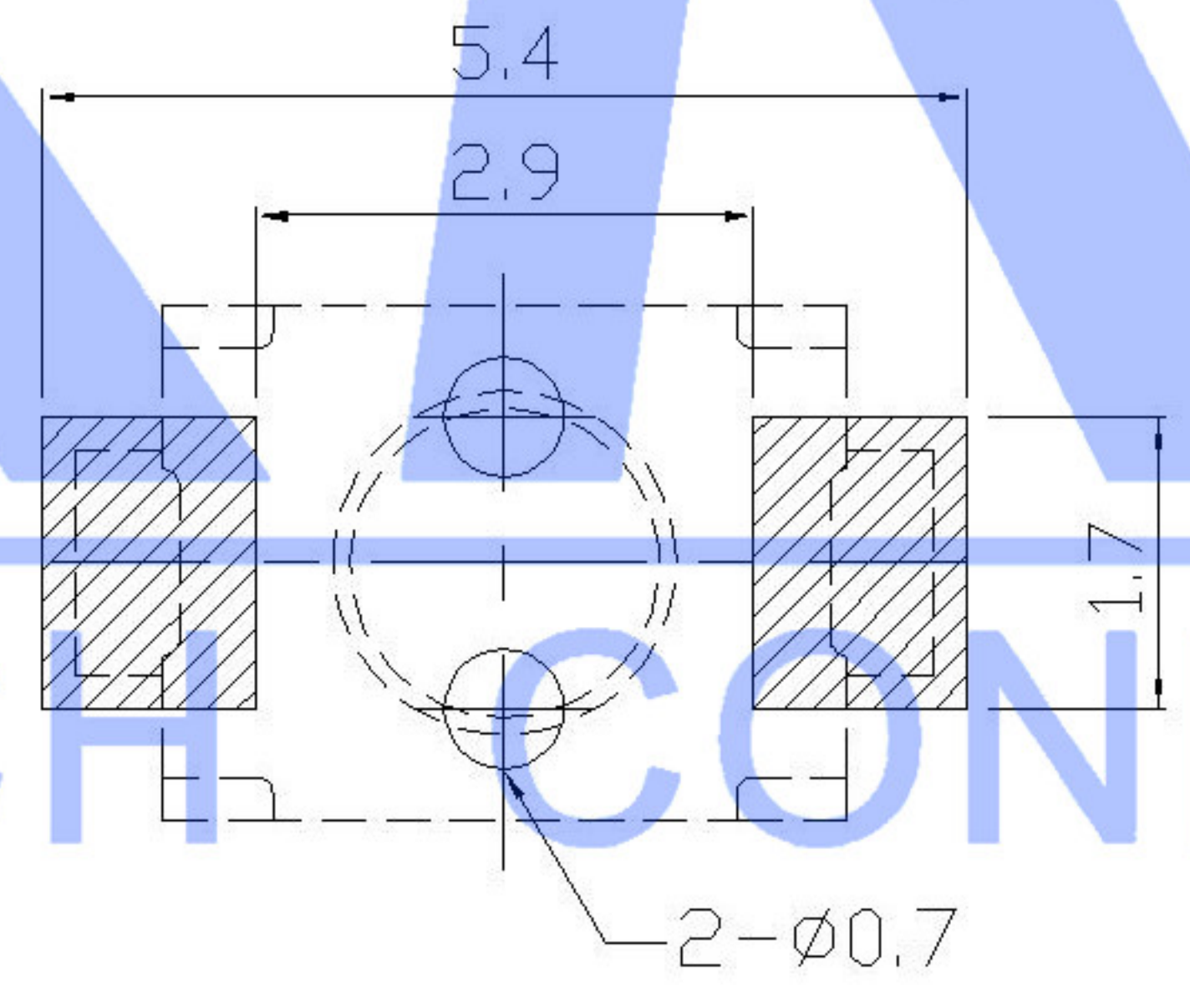
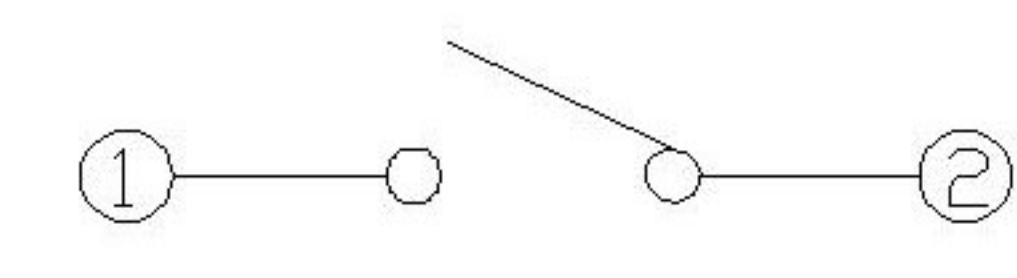




P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



CIRCUIT DIAGRAM



SPECIFICATION

Contact Rating	50mA 12V DC
Contact Resistance	100mΩ max.
Insulation Resistance	100MΩ min. 500V DC
Dielectric Strength	250V AC/1 minute
Travel	0.25mm
Operating Temp.	-25°C ~ +70°C
Storage Temp.	-30°C ~ +80°C

PAPT NO	TS-1185-X-X-X-A
Operating Force	A:100gf B:160gf C:260gf
Height	H: A:2.0 B:2.5
	A:With B:Without
Keystake	A:PA16 B:Silica gel

⑤	Terminal	—	2	Brass (0.30t)	ag Plated	—
④	Contact	—	1	F.ag/SUS		—
③	Base	—	1	PA46	Natural	—
②	Cover	—	1	Brass	Tin plated	—
①	Keystake	—	1	PA46		—
ITEM	PAPT NAMF	TER,NO	QTY	MATERIAL	FINISHING	REMARK

										DSND		DATE		SCALE: N/A	MODEL TYPE: TACT SWITCH		
					units:	mm				DWN		DATE		VIEW: 	PART NO.:		
△X					tolerance:					CHKD		DATE		UNIT: mm	DWG NO.:		
△X						X.X	±0.2mm								TS-1185-X-X-X-A		
△X						X.XX	±0.1mm										
MARK	DESCRIPTION			DATE	REVISED	APPROVED	X.XXX	±0.05mm		APPD		DATE		SIZE: A4			
REVISIONS							UNSPECIFIED TOLERANCES			XKB INDUSTRIAL PRECISION CO.,LIMITED					WEIGHT	SHEET	REVISION
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn															1.0g	1/1	A0